

High Q Wire Wound Ceramic Chip Inductors - MS2012HQ SERIES

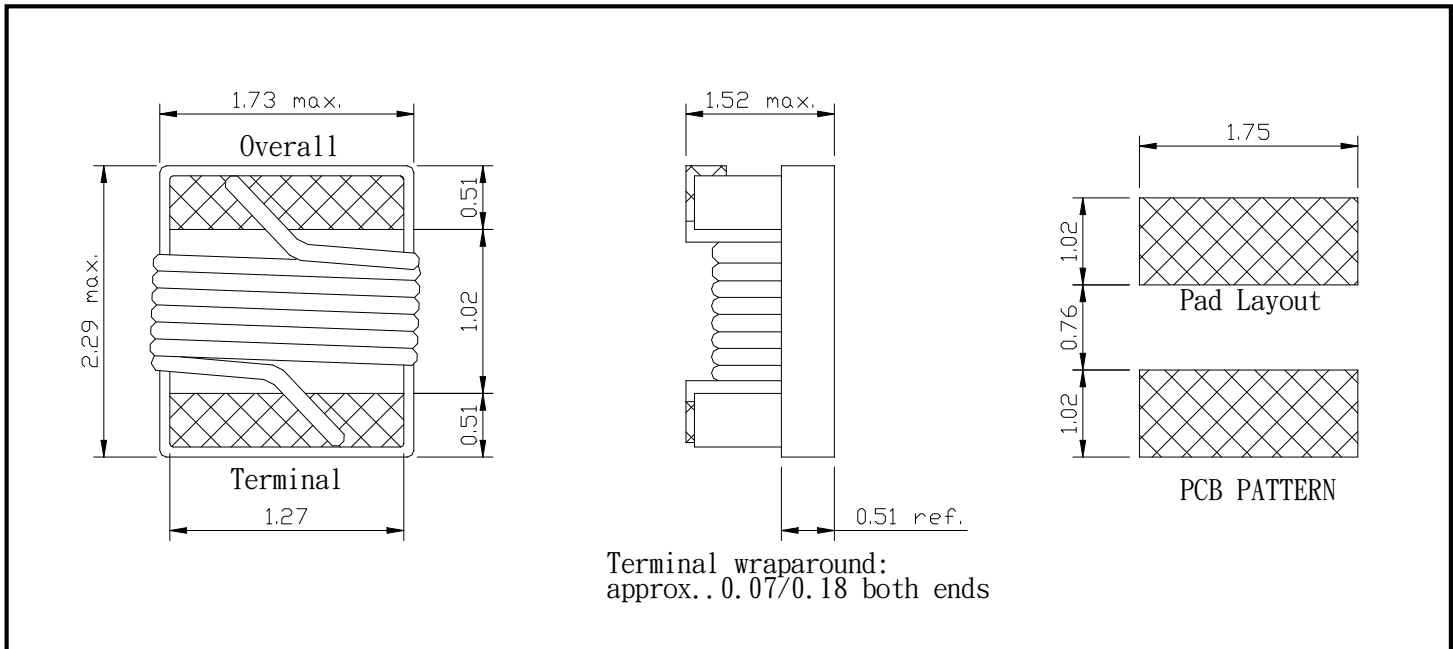


PART NUMBERING SYSTEM

MS	2012HQ	—	12NJ	—	LF
TYPE	DIMENSIONS		INDUCTANCE		LEAD FREE

SHAPES AND DIMENSIONS

UNIT : mm



SPECIFICATION TABLE

PART NUMBER	INDUCTANCE (nH)	TOLERANCE	Q. MIN.	SRF (GHz) MIN.	DCR (Ω) (max)	IDC (A) (max)
MS2012HQ-2N5X-LF	2.5@250MHz	B,S	80@1500MHz	10.30	0.020	1.60
MS2012HQ-5N6X-LF	5.6@250MHz	B,S	98@1500MHz	6.10	0.035	1.60
MS2012HQ-6N2X-LF	6.2@250MHz	B,S	88@1000MHz	4.75	0.035	1.60
MS2012HQ-12NX-LF	12@250MHz	K,J,G	80@1000MHz	3.00	0.045	1.60
MS2012HQ-16NX-LF	16@250MHz	K,J,G	72@500MHz	2.95	0.060	1.50
MS2012HQ-18NX-LF	18@250MHz	K,J,G	75@500MHz	2.55	0.060	1.40
MS2012HQ-20NX-LF	20@250MHz	K,J,G	70@500MHz	2.05	0.065	1.40



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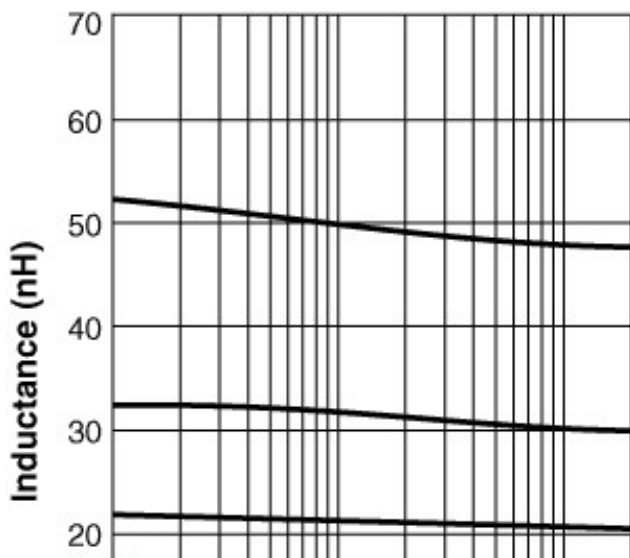


SPECIFICATION TABLE

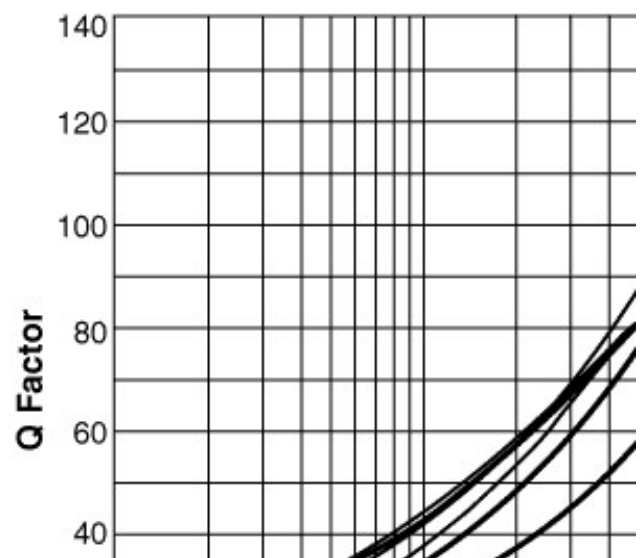
PART NUMBER	INDUCTANCE (nH)	TOLERANCE	Q. MIN.	SRF (GHz) MIN.	DCR (Ω) (max)	IDC (A) (max)
MS2012HQ-27NX-LF	27@250MHz	K,J,G	75@500MHz	2.00	0.070	1.30
MS2012HQ-30NX-LF	30@250MHz	K,J,G	65@500MHz	1.95	0.095	1.20
MS2012HQ-39NX-LF	39@250MHz	K,J,G	65@500MHz	1.60	0.110	1.10
MS2012HQ-48NX-LF	48@200MHz	K,J,G	65@500MHz	1.40	0.095	1.20
MS2012HQ-51NX-LF	51@200MHz	K,J,G	65@500MHz	1.40	0.120	1.00

TYPICAL ELECTRICAL CHARACTERISTICS

INDUCTANCE vs. FREQUENCY CHARACTERISTICS



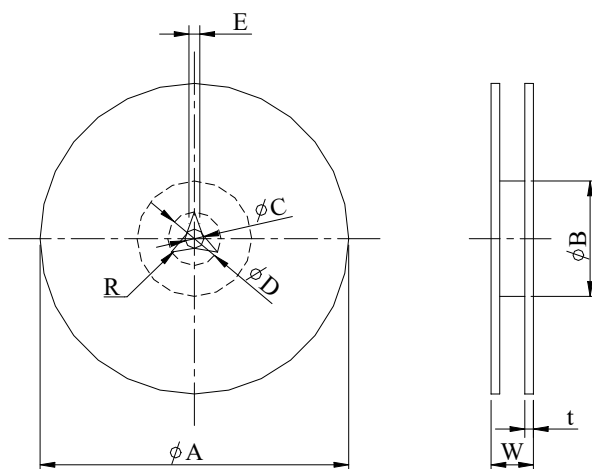
Q vs. FREQUENCY CHARACTERISTICS



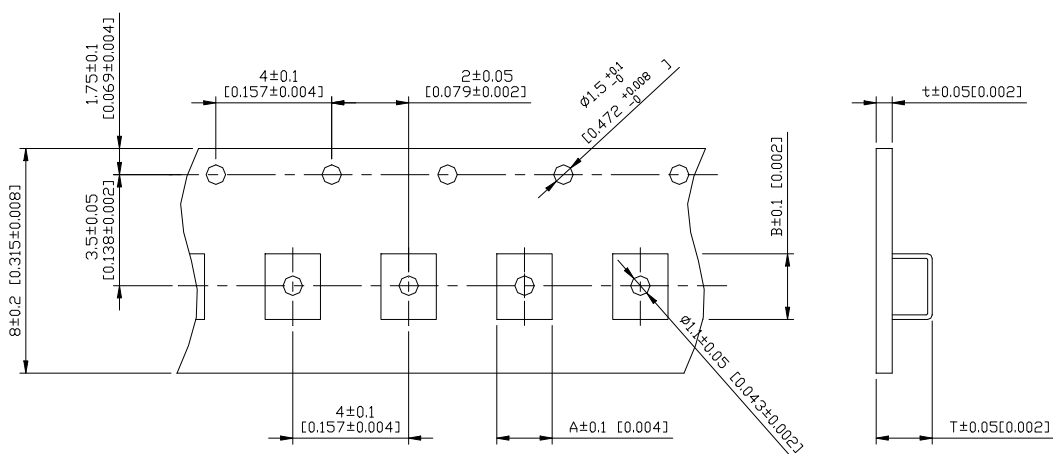
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PACKAGING SPECIFICATION



	A	B	C	D	E	W8	W12	t	R
T(ψ178mm) Reel	ψ178±2	ψ60±1	ψ13±0.8	ψ21±0.8	2	10±1.5	14.5±1.5	1.27±0.2	1



TYPE	A	B	T	t	T(ψ178mm)	T(ψ330mm)
MS2012HQ	1.55	2.30	1.20	0.2	2000 pcs/reel	-